

PATENT ASSIGNMENT COVER SHEET

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 Stylesheet Version v1.2

EPAS ID: PAT6891232

| | | |
|---|---|-----------------------|
| SUBMISSION TYPE: | NEW ASSIGNMENT | |
| NATURE OF CONVEYANCE: | ASSIGNMENT | |
| CONVEYING PARTY DATA | | |
| | Name | Execution Date |
| | YASUAKI AOYAMA | 06/30/2021 |
| | RYOSUKE HOSHI | 06/30/2021 |
| | HIROYUKI KOBAYASHI | 07/12/2021 |
| | SATORU KANEKO | 06/30/2021 |
| | TAKESHI TAMAKOSHI | 07/12/2021 |
| | HIROSHI WATANABE | 07/13/2021 |
| | KATSUHIRO KAMBARA | 07/12/2021 |
| | KUNIAKI ONIZAWA | 07/13/2021 |
| RECEIVING PARTY DATA | | |
| Name: | HITACHI HIGH-TECH CORPORATION | |
| Street Address: | 17-1, TORANOMON 1-CHOME | |
| City: | MINATO-KU, TOKYO | |
| State/Country: | JAPAN | |
| Postal Code: | 105-6409 | |
| PROPERTY NUMBERS Total: 1 | | |
| | Property Type | Number |
| | Application Number: | 17434945 |
| CORRESPONDENCE DATA | | |
| Fax Number: | (202)624-8844 | |
| <i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i> | | |
| Phone: | 2026242800 | |
| Email: | ehorne@crowell.com, edocket@crowell.com | |
| Correspondent Name: | CROWELL & MORING LLP | |
| Address Line 1: | P.O. BOX 14300 | |
| Address Line 4: | WASHINGTON, D.C. 20011-4300 | |
| ATTORNEY DOCKET NUMBER: | 108147.PE852US | |
| NAME OF SUBMITTER: | MICHAEL H. JACOBS | |
| SIGNATURE: | /Michael H. Jacobs/ | |

| | |
|---|------------|
| DATE SIGNED: | 08/30/2021 |
| Total Attachments: 6 source=PE852US_Assignment#page1.tif source=PE852US_Assignment#page2.tif source=PE852US_Assignment#page3.tif source=PE852US_Assignment#page4.tif source=PE852US_Assignment#page5.tif source=PE852US_Assignment#page6.tif | |

ASSIGNMENT (譲渡証)

As a below named inventor, I hereby declare that:

IN CONSIDERATION of the sum of One Dollar (\$1.00) or the equivalent thereof, and other good and valuable consideration paid to me citizen of Japan by HITACHI HIGH-TECH CORPORATION, a corporation organized under the laws of Japan, located at 17-1, Toranomon 1-chome, Minato-ku, Tokyo 105-6409 Japan receipt of which is hereby acknowledged I do hereby sell and assign to said HITACHI HIGH-TECH CORPORATION,

its successors and assigns, all my right, title and interest, in and for the United States of America, in and to
CONVEYING DEVICE, SAMPLE ANALYSIS SYSTEM AND SAMPLE PRETREATMENT DEVICE
INCLUDING THE CONVEYING DEVICE, AND METHOD FOR CONVEYING CONVEYANCE
OBJECT

invented by me (if only one is named below) or us (if plural inventors are named below) and described in the application for United States Letters Patent therefor, executed on even date herewith, and all United States Letters Patent which may be granted therefor, and all divisions, continuations and extensions thereof, the said interest being the entire ownership of the said Letters Patent when granted,

to be held and enjoyed by said HITACHI HIGH-TECH CORPORATION,

its successors, assigns or other legal representatives, to the full end of term for which said Letters Patent may be granted as fully and entirely as the same would have been held and enjoyed by me or us if this assignment and sale had not been made;

And I hereby agree to sign and execute any further documents or instruments which may be necessary, lawful, and proper in the prosecution of the above-named application or in the preparation and prosecution of any continuing, continuation-in-part, substitute, divisional, renewal, reviewed or reissue applications or in any amendment, extension, or interference proceedings, or otherwise to secure the title thereto in said assignee;

And I do hereby authorize and request the Commissioner of Patents to issue said Letters Patent to said HITACHI HIGH-TECH CORPORATION.

Signed on the date(s) indicated aside our signatures:

INVENTOR(S)
(発明者フルネームサイン)

Date Signed
(署名日)

1) Yasuaki Aoyama Yasuaki AOYAMA

6/30/2021

2) Ryosuke Hoshi Ryosuke HOSHI

6/30/2021

3) Hiroyuki KOBAYASHI

4) *Satoru Kaneko* Satoru KANEKO

6/30/2021

5) Takeshi TAMAKOSHI

6) Hiroshi WATANABE

7) Katsuhiro KAMBARA

8) Kuniaki ONIZAWA

9)

10)

PATENT
REEL: 057330 FRAME: 0744

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|---|----------------------|
| 1) _____ Yasuaki AOYAMA | _____ |
| 2) _____ Ryosuke HOSHI | _____ |
| 3) <u>Hiroyuki Kobayashi</u> Hiroyuki KOBAYASHI | <u>7/12/2021</u> |
| 4) _____ Satoru KANEKO | _____ |
| 5) _____ Takeshi TAMAKOSHI | _____ |
| 6) _____ Hiroshi WATANABE | _____ |
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| 4) _____ Satoru KANEKO | _____ |
| 5) <u>Takeshi Tamakoshi</u> Takeshi TAMAKOSHI | <u>July 12, 2021</u> |
| 6) _____ Hiroshi WATANABE | _____ |
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| 6) <u>Hiroshi Watanabe</u> Hiroshi WATANABE | <u>July 13, 2021</u> |
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| 8) <u>Kuniaki ONIZAWA</u> Kuniaki ONIZAWA | <u>13.7.2021</u> |
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